

ABSTRACT

A solder paste printing method comprising the steps of
dispose a plate-shaped mask having a plurality of through holes
5 formed to correspond to a plurality of connection terminals,
over a printed face of a substantially polygonal wiring substrate
having a side of a length of at least 300 mm and having the
connection terminals in the printed face; forming
solder-printed layers by moving a squeegee along an outer face
10 of the mask while holding the squeegee in contact with the outer
face of the mask, thereby to fill the through holes with a solder
paste; and detaching the mask by disengaging one side edge of
the mask disposed over the printed face of the wiring substrate,
relatively from the printed face.

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